

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0737821100](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 144 Circuits

Documents:

[3D Model](#) [Product Specification PS-73780-999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

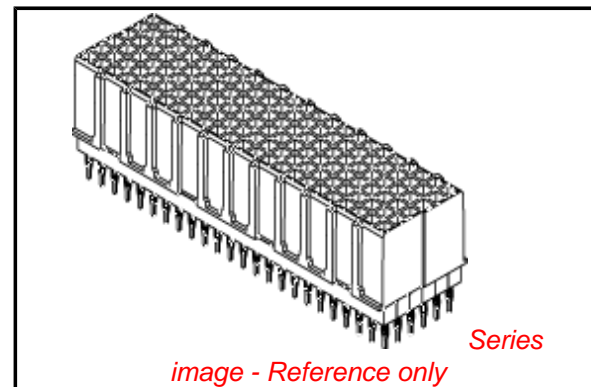
CSA LR19980
 UL E29179

General

Product Family Backplane Connectors
 Series [73782](#)
 Application Backplane, Mezzanine
 Component Type PCB Header
 Overview [hdm](#)
 Product Name HDM®
 Style N/A

Physical

Circuits (Loaded) 144
 Circuits (maximum) 144
 Color - Resin Black
 Durability (mating cycles max) 200
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part No
 Keying to Mating Part None
 Material - Metal Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Tin-Lead
 Material - Resin High Temperature Thermoplastic
 Number of Columns 24
 Number of Pairs Open Pin Field
 Number of Rows 6
 Orientation Vertical
 PC Tail Length (in) 0.079 In
 PC Tail Length (mm) 2.00 mm
 PCB Retention None
 PCB Thickness Recommended (in) 0.055 In
 PCB Thickness Recommended (mm) 1.40 mm
 Packaging Type Tube
 Pitch - Mating Interface (in) 0.079 In
 Pitch - Mating Interface (mm) 2.00 mm
 Plating min: Mating (µin) 30
 Plating min: Mating (µm) 0.75
 Plating min: Termination (µin) 100
 Plating min: Termination (µm) 2.5
 Polarized to PCB No
 Stackable Yes
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -55°C to +105°C



EU RoHS

**ELV and RoHS
 Compliant**
**REACH SVHC
 Contains SVHC: No**
**Halogen-Free
 Status
 Not Reviewed**

China RoHS



**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of
 Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
 non-product compliance questions.

Search Parts in this Series

[73782Series](#)

Mates With

[73632 HDM PLUS® Board-to-Board
 Daughtercard Receptacle. \[73780 HDM®
 Board-to-Board Daughtercard Receptacle\]\(#\)](#)

Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	100V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

Material Info

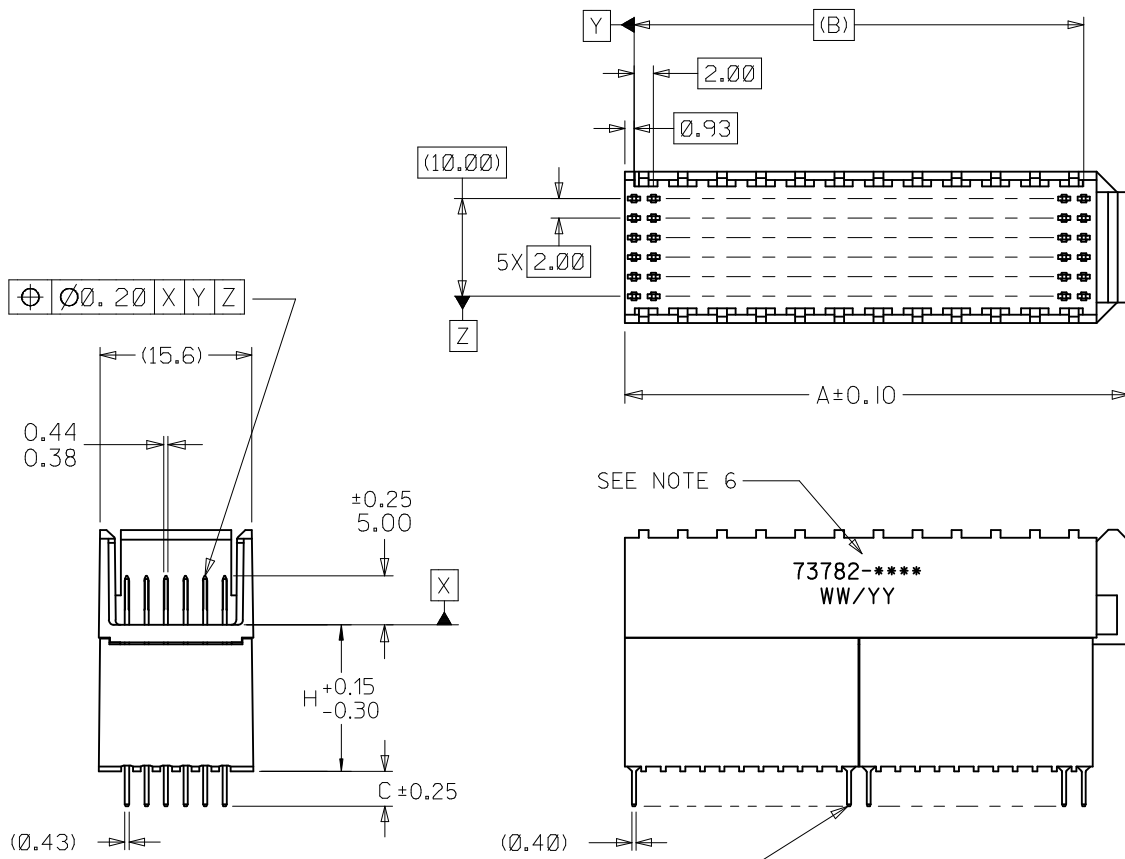
Reference - Drawing Numbers

Packaging Specification	PK-70873-0870
Product Specification	PS-73780-999
Sales Drawing	SD-73782-001

HDM and High Density Metric are trademarks of Amphenol Corporation

This document was generated on 05/14/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION



NOTES:

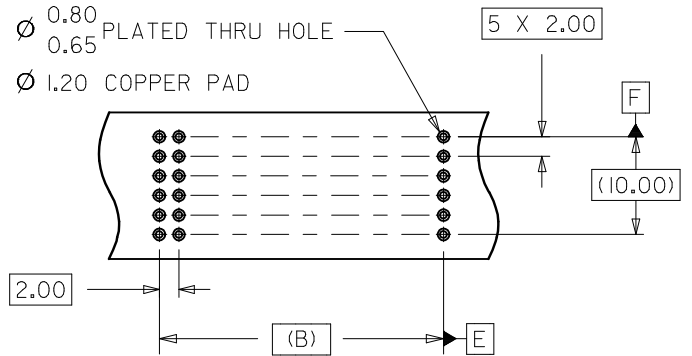
- MATERIALS: HOUSING-LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK. TERMINAL-PHOSPHOR BRONZE
- FINISH:
0.75 MICROMETERS MINIMUM SELECTIVE GOLD IN MATING AREA
2.50 MICROMETERS MINIMUM SELECTIVE TIN IN TAIL AREA
NICKEL UNDERPLATE OVERALL.
- THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
- THIS PART CONFORMS TO MOLEX COSMETIC SPECIFICATION PS-45499-002 CLASS C.
- PACKAGE PER PK-70873-0870, PK-70873-0871, OR PK-70873-0875.
- PARTS MARKED WITH PART NUMBER AND DATE CODE APPROXIMATELY WHERE SHOWN.

$\varnothing 0.15$ E F

$\varnothing 0.838$ DRILL

$\varnothing 0.80$
 $\varnothing 0.65$ PLATED THRU HOLE

$\varnothing 1.20$ COPPER PAD



BACKPLANE HOLE PATTERN

$\varnothing 0.15$ X Y Z

REVISE DIM H TOL EC NO: UCP2008-3186 DRWN:SDANNELLEY 2008/07/29 CHKD:MS:IBARRA 2008/09/11 APPR:SMILLER 2008/09/16	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$ $\sphericalangle=0$	mm INCH 4 PLACES \pm --- \pm --- 3 PLACES \pm --- \pm --- 2 PLACES ± 0.05 \pm --- 1 PLACE ± 0.10 \pm --- ANGULAR $\pm 1/2^\circ$	MM ONLY	2:1	METRIC	
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE JB INGHAM 1997/04/25 CHECKED BY DATE SREED 1997/04/25 APPROVED BY DATE CB IXLER 1997/04/25	TITLE	SALES ASSEMBLY, HDM BACKPLANE STACKING MOD CLOSED END SOLDER	
	REV		MATERIAL NO.	SEE TABLE	DOCUMENT NO.	MOLEX INCORPORATED SD-73782-001

MATERIAL NUMBER ASSIGNMENT

73782-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "C"
0	72	27.6	22.00	2.0
1	144	51.6	46.00	2.0
2	72	27.6	22.00	2.5
3	144	51.6	46.00	2.5
4	72	27.6	22.00	3.0
5	144	51.6	46.00	3.0
6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "H"
1	15.05
2	6.05
3	10.05

SEE SHEET 1 EC NO: UCP2008-3186 DRWN: SPANNELLY 2008/07/29 CHK: MSIBARRA 2008/09/11 APPR: SMILLER 2008/09/16	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▼=0 ▽=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.05 ± --- 1 PLACE ± 0.10 ± --- ANGULAR ± 1/2°	MM ONLY	1:1	METRIC	DRAWN BY DATE JB INGHAM 1997/04/25 CHECKED BY DATE SREED 1997/04/25 APPROVED BY DATE CB IXLER 1997/04/25	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	TITLE SALES ASSEMBLY, HDM BACKPLANE STACKING MOD CLOSED END SOLDER		MOLEX INCORPORATED DOCUMENT NO. SD-73782-001	SHEET NO. 2 OF 2
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

MATERIAL NUMBER ASSIGNMENT

73782-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "C"
0	72	27.6	22.00	2.0
1	144	51.6	46.00	2.0
2	72	27.6	22.00	2.5
3	144	51.6	46.00	2.5
4	72	27.6	22.00	3.0
5	144	51.6	46.00	3.0
6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "H"
1	15.05
2	6.05
3	10.05

SEE SHEET 1 EC NO: UDT2000-1073 DRWN: BINGHAM 00/05/08 CHK: REED 00/05/08 APPR: BIXLER 00/05/08	QUALITY SYMBOLS MAJOR = 0 CRITICAL = 0	GENERAL TOLERANCES: (UNLESS SPECIFIED)	SCALE: NO: NE	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	DIMENSIONS: <input type="checkbox"/> mm INCH <input type="checkbox"/> INCH mm <input checked="" type="checkbox"/> mm ONLY	SHT REV REVISION ON CAD ONLY	
	MAJOR = 0 CRITICAL = 0	4 PLACES ±0. ±.	DRAWN BY & DATE JBINGHAM 97/04/25	TITLE: SALES ASSEMBLY HDM BACKPLANE STACKING MODULE CLOSED END OPTION SOLDER TAIL			
		3 PLACES ±0. ±.	CHECKED BY & DATE SREED 97/04/25	MOLEX INCORPORATED			
		2 PLACES ±0.N/A ±.	APPROVED BY & DATE CBIXLER 97/04/25	CAD FILENAME S73782X2.DGN	MATERIAL NO. SEE CHART	DRAWING NO. SD-73782-001	SHEET NO. 2
F	REV	1 PLACE ±0.NA/ ±.	ANGLAR: ± °				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE B				